

S1ZA60

600V 1.1A

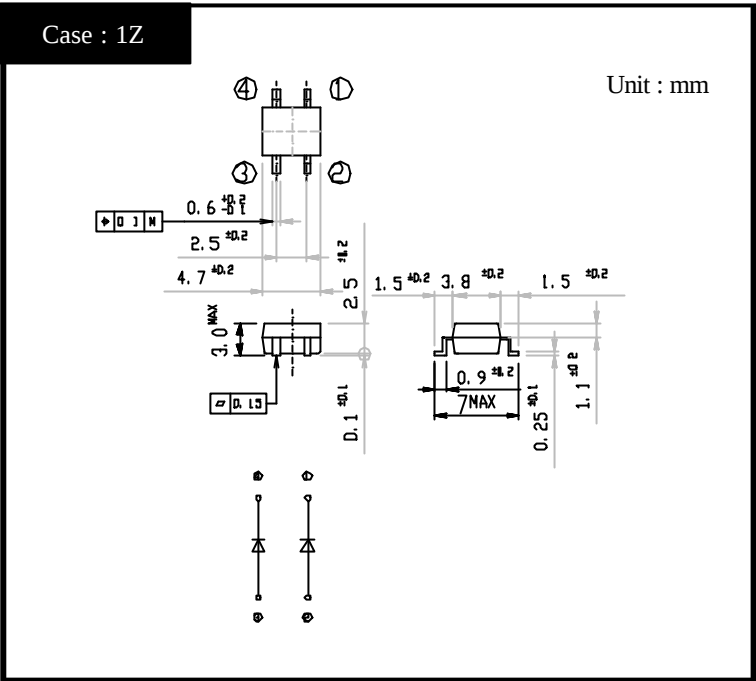
FEATURES

- Small SMT package
- Array
- High reliability with superior moisture resistance
- Applicable to Automatic Insertion

APPLICATION

- Conventional Rectification
- Motor
- Home Appliances, Office Equipment
- Telecommunication, Factory Automation

OUTLINE DIMENSIONS



RATINGS

• Absolute Maximum Ratings (If not specified Tl=25)

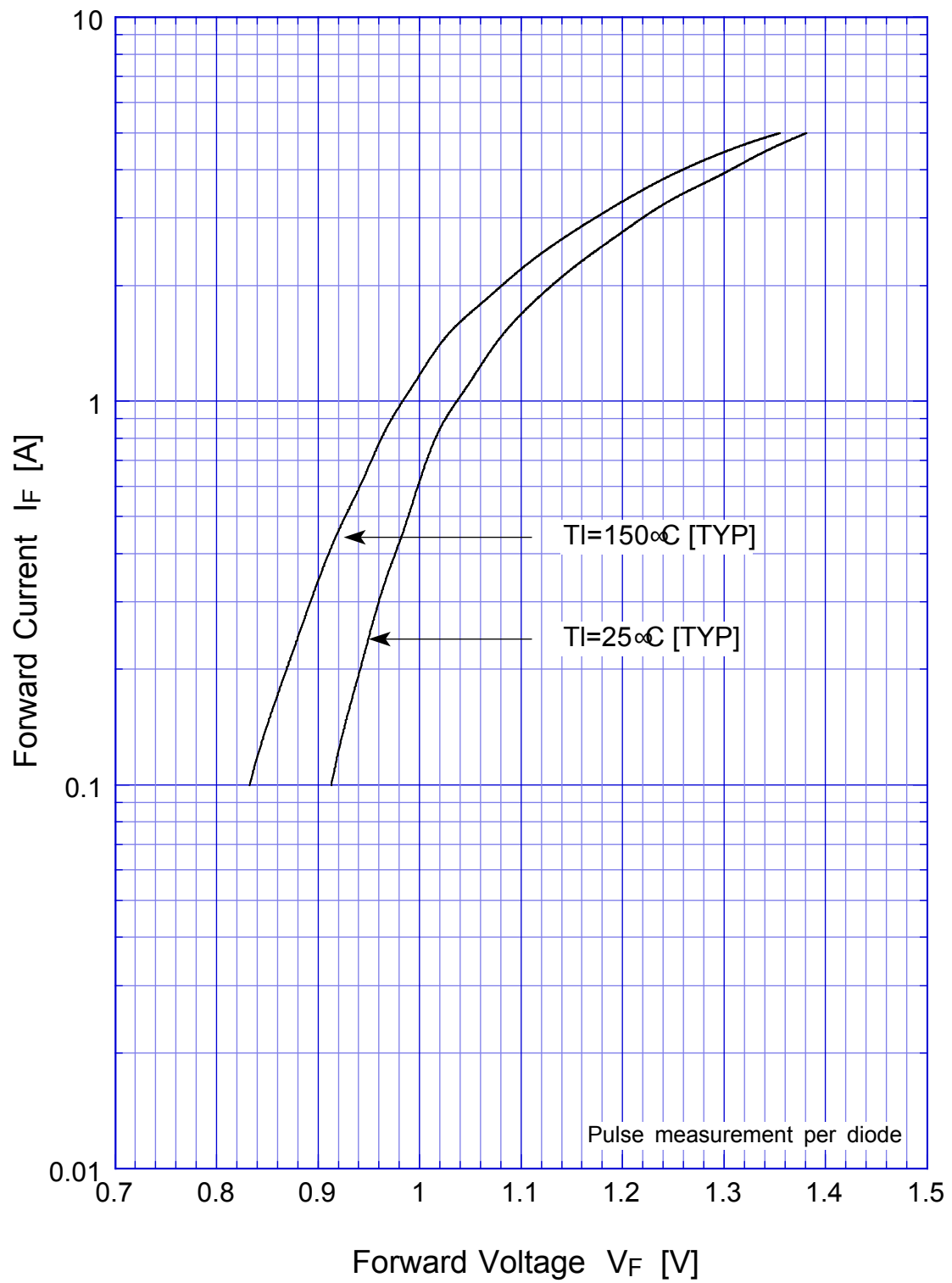
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	Tstg		-40 ~ 150	
Operating Junction Temperature	Tj		150	
Maximum Reverse Voltage	V _{RM}		600	V
Average Rectified Forward Current	I _O	50Hz sine wave, R-load, Ta=25 On alumina substrate 1 element operation	1.1	A
		50Hz sine wave, R-load, Ta=25 On alumina substrate 2 element operation	0.8	
		50Hz sine wave, R-load, Ta=25 On glass-epoxy substrate 1 element operation	0.9	
		50Hz sine wave, R-load, Ta=25 On glass-epoxy substrate 2 element operation	0.63	
Peak Surge Forward Current	I _{FSM}	50Hz sine wave, Non-repetitive 1cycle peak value, Tl=25	30	A

• Electrical Characteristics (If not specified Tl=25)

Item	Symbol	Conditions	Ratings	Unit
Forward Voltage	V _F	IF=0.9A, Pulse measurement, Rating of per diode	Max.1.1	V
Reverse Current	I _R	V _R =V _{RM} , Pulse measurement, Rating of per diode	Max.10	μA
Thermal Resistance	θ ja	unction to ambient On alumina substrate 1 element operation	Max.93	/W
		unction to ambient On alumina substrate 2 element operation	Max.140	
		unction to ambient On glass-epoxy substrate 1 element operation	Max.120	
		unction to ambient On glass-epoxy substrate 2 element operation	Max.186	

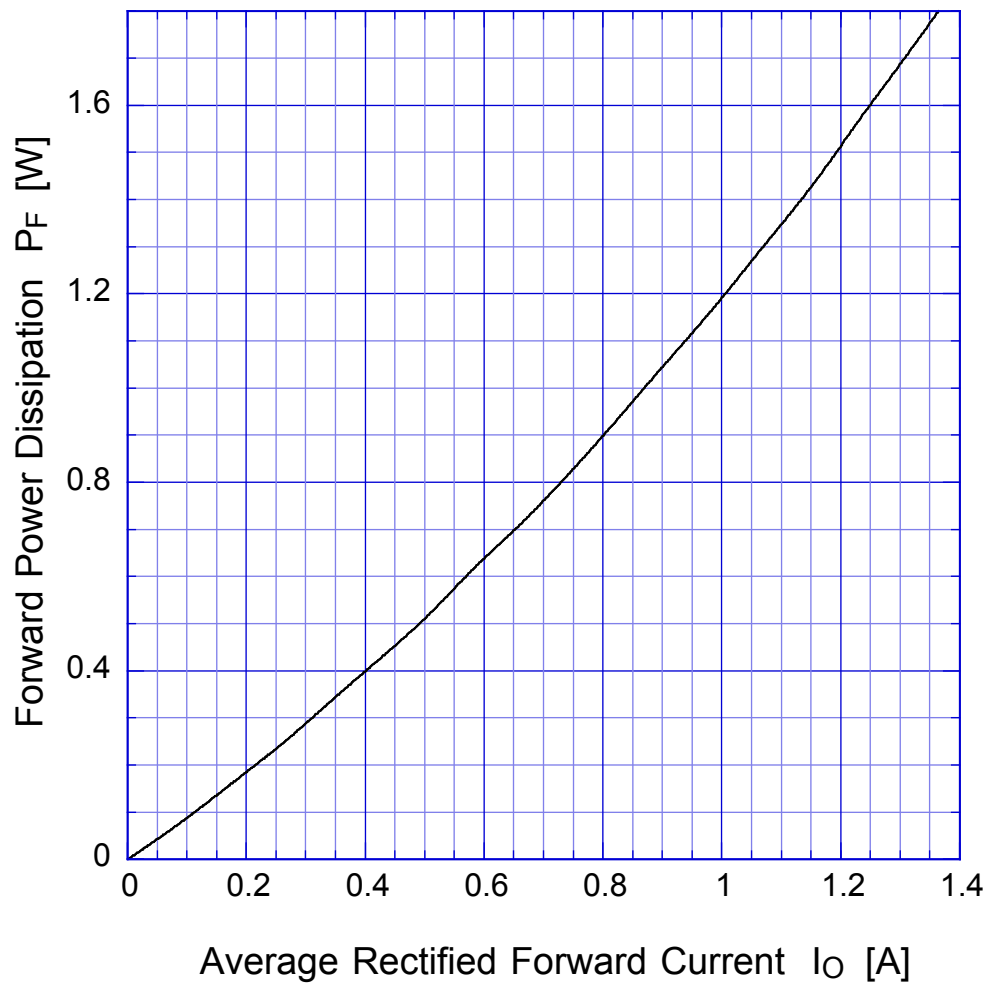
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Forward Voltage



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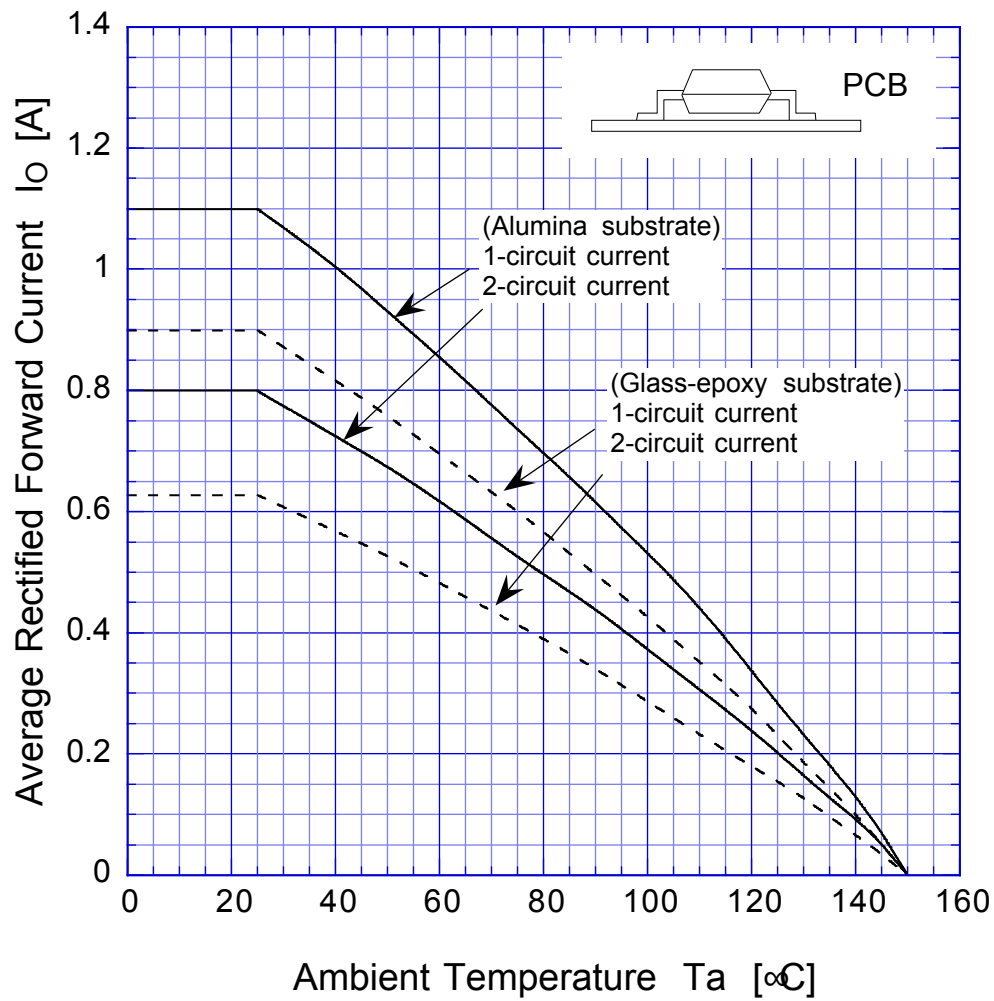
Forward Power Dissipation



$T_j = 150^\circ\text{C}$
Sine wave

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Derating Curve



Alumina substrate
Soldering land 1mmf
Conductor layer 20mm
Substrate thickness 0.64mm

Glass-epoxy substrate
Soldering land 1mmf
Conductor layer 35mm

Sine wave
R-load
Free in air

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Peak Surge Forward Capability

